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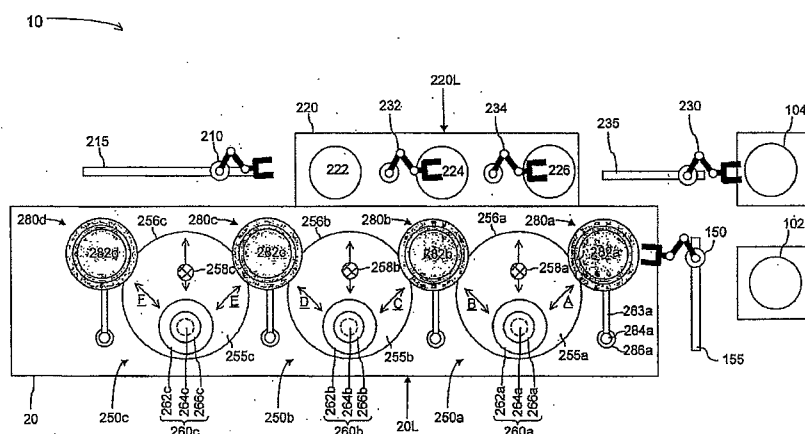
(71) Applicant and
(72) Inventor (*for all designated States except US*): **INKWON, Jeong** [KR/US]; 10697 Rosewood Road, #D, Cupertino, CA 95014 (US).
(74) Agent: **HAM, Thomas, H.**; Wilson & Ham, PMB: 348, 2530 Berryessa Road, San Jose, CA 95132 (US).

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(54) Title: APPARATUS AND METHOD FOR POLISHING SEMICONDUCTOR WAFERS USING ONE OR MORE POLISHING SURFACES



(57) Abstract: An apparatus and method for polishing objects, such as semiconductor wafers, utilizes one or more polishing surfaces, multiple wafer carriers and at least one load-and-unload cup. The load-and-unload cup may be configured to move to and from the wafer carriers in a pivoting manner. The load-and-unload cup may be configured to move to and from the wafer carriers in a linear reciprocating manner. The wafer carriers may be configured to move to and from the load-and-unload cup in a pivoting manner. The wafer carriers may be configured to move to and from the load-and-unload cup in a linear reciprocating manner.